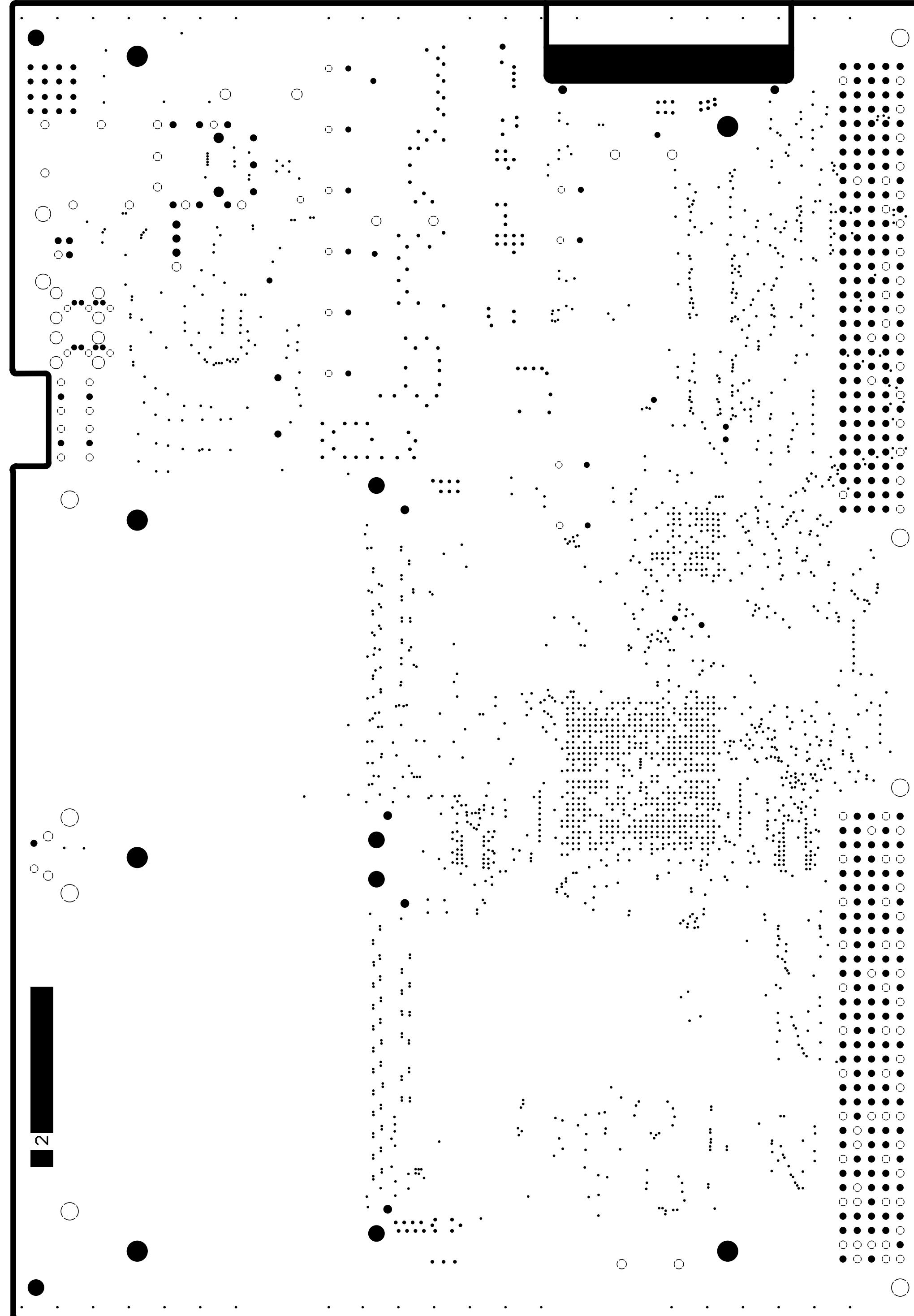
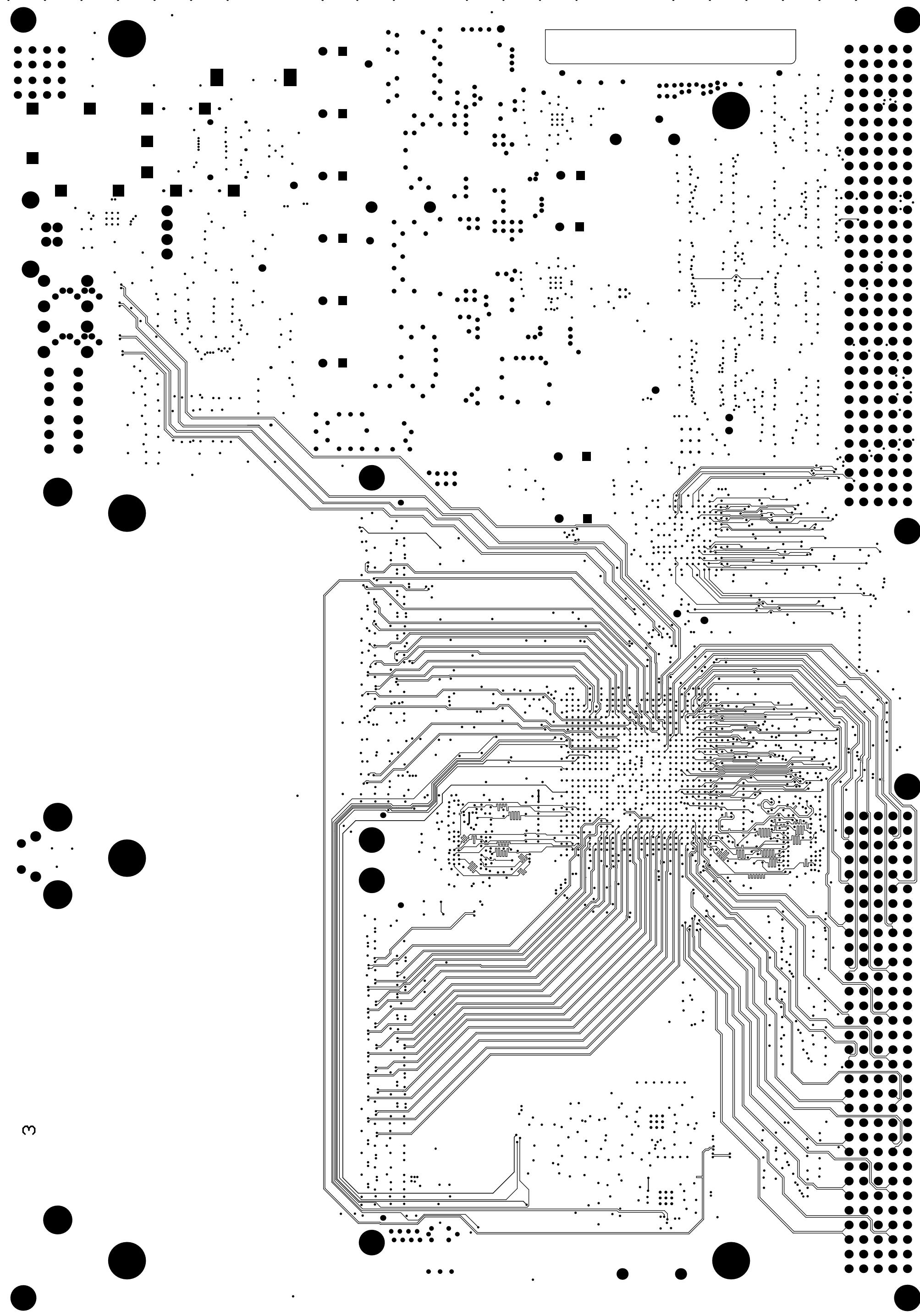
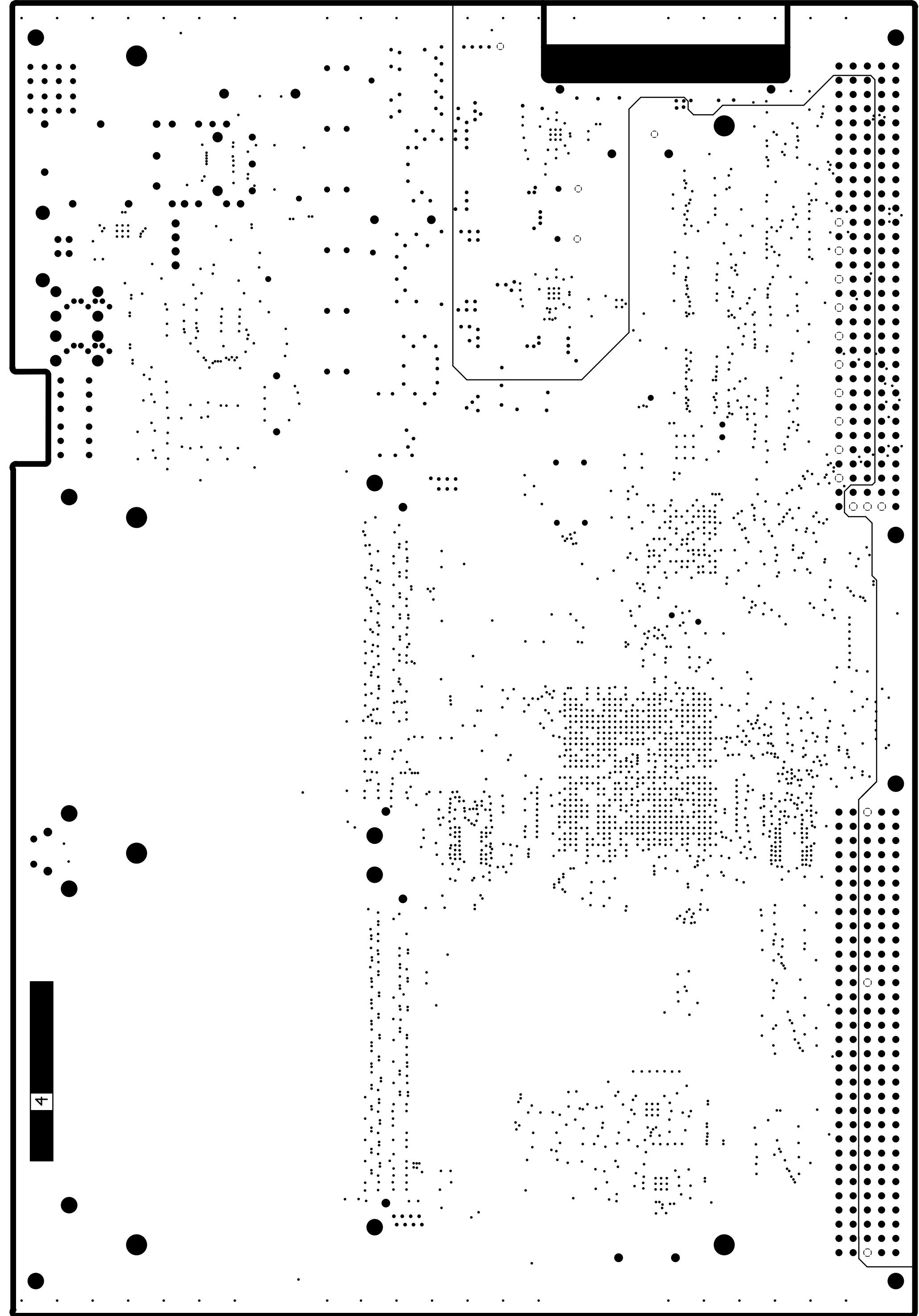
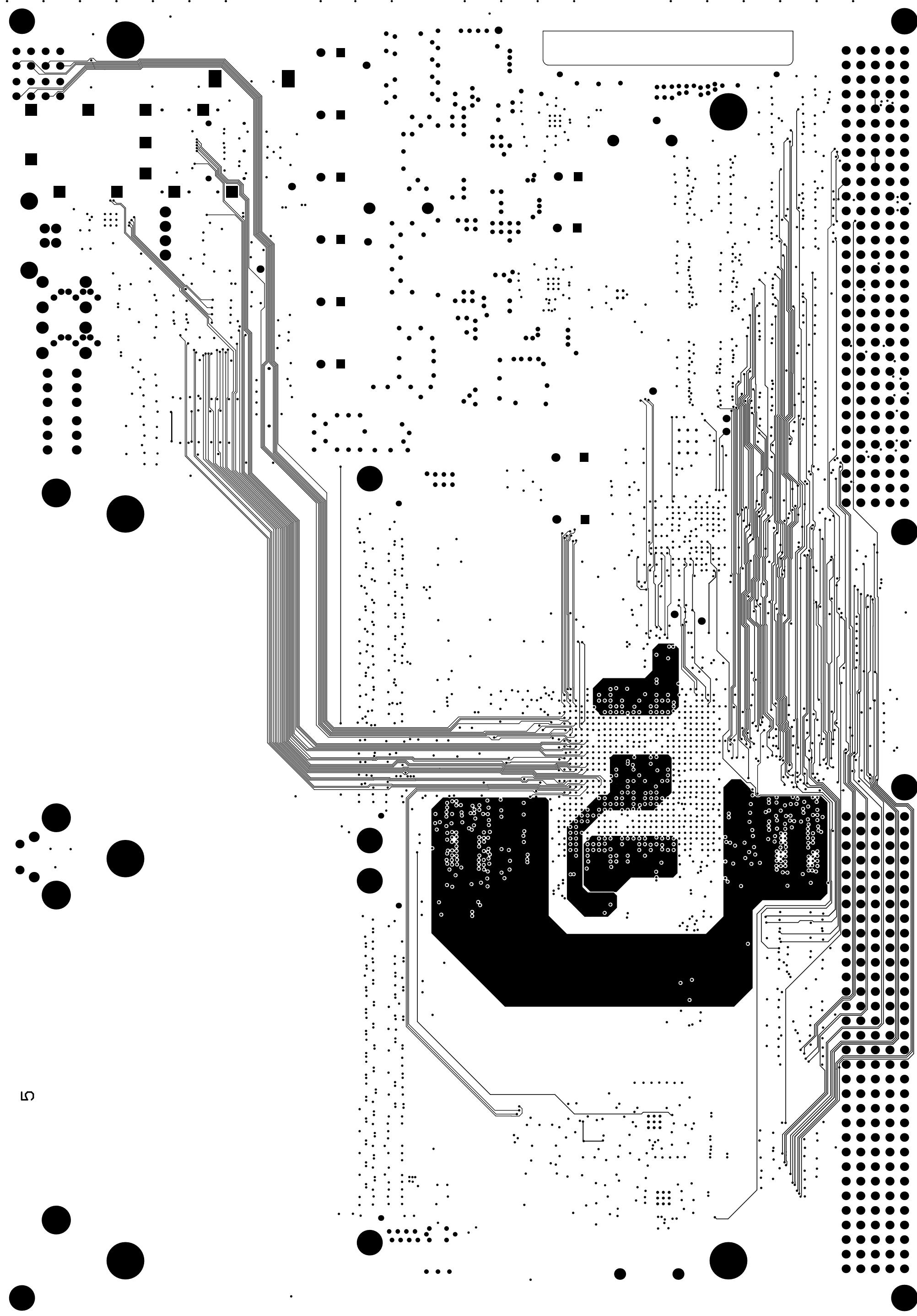


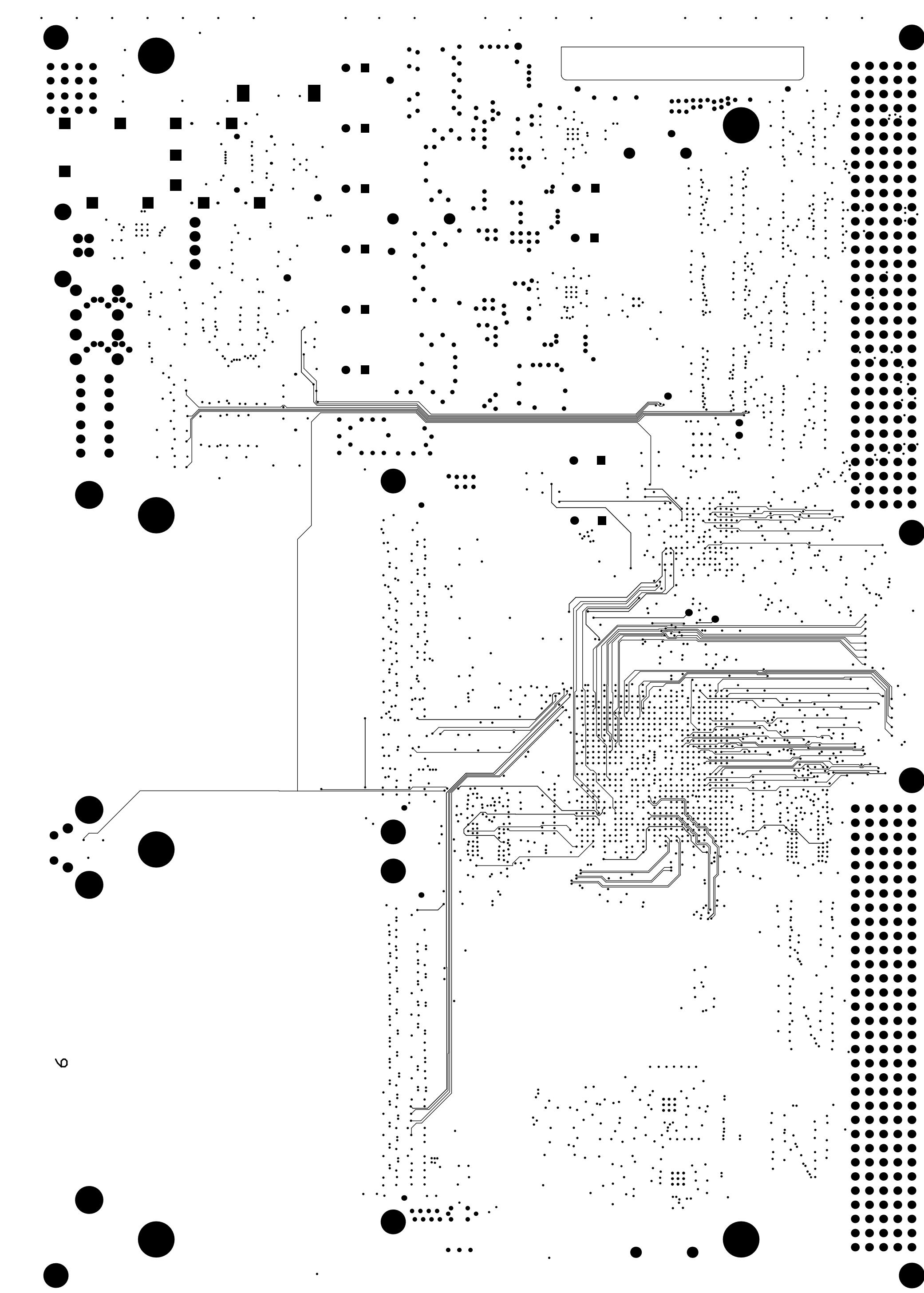
Layer Stack Up Detail for: SUEC.pcbdoc						
Layer Name	Top Solder Mask	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant
Top Layer	(.GTL)	0.709mil	3.937mil	FR-4	4.60	Core
L2 GND	(.GP1)	0.709mil	5.905mil	FR-4	4.80	PrePreg
L3	(.G1)	0.709mil	5.905mil	FR-4	4.80	Core
L4 PWR3.3	(.GP2)	0.709mil	3.937mil	FR-4	4.80	PrePreg
L5	(.G2)	0.709mil	11.811mil	FR-4	4.80	Core
L6	(.G3)	0.709mil	3.937mil	FR-4	4.80	PrePreg
L7 GND	(.GP3)	0.709mil	5.905mil	FR-4	4.80	Core
L8	(.G4)	0.709mil	5.905mil	FR-4	4.80	PrePreg
L9 PWR	(.GP4)	0.709mil	3.937mil	FR-4	4.80	Core
Bottom Layer	(.GBL)	0.709mil	0.394mil	Solder Resist	3.50	Core
Bottom Solder Mask	(.GBS)					

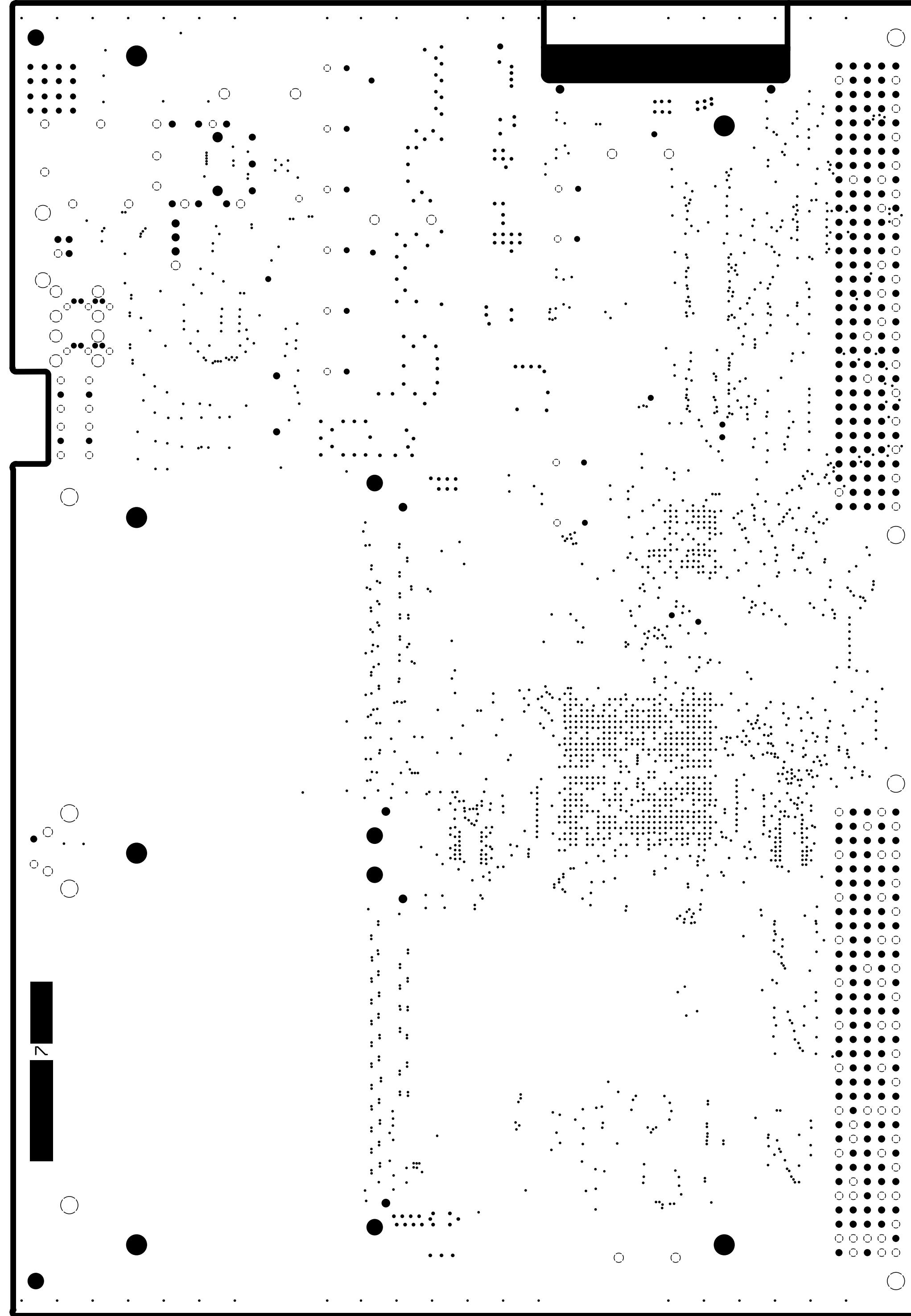


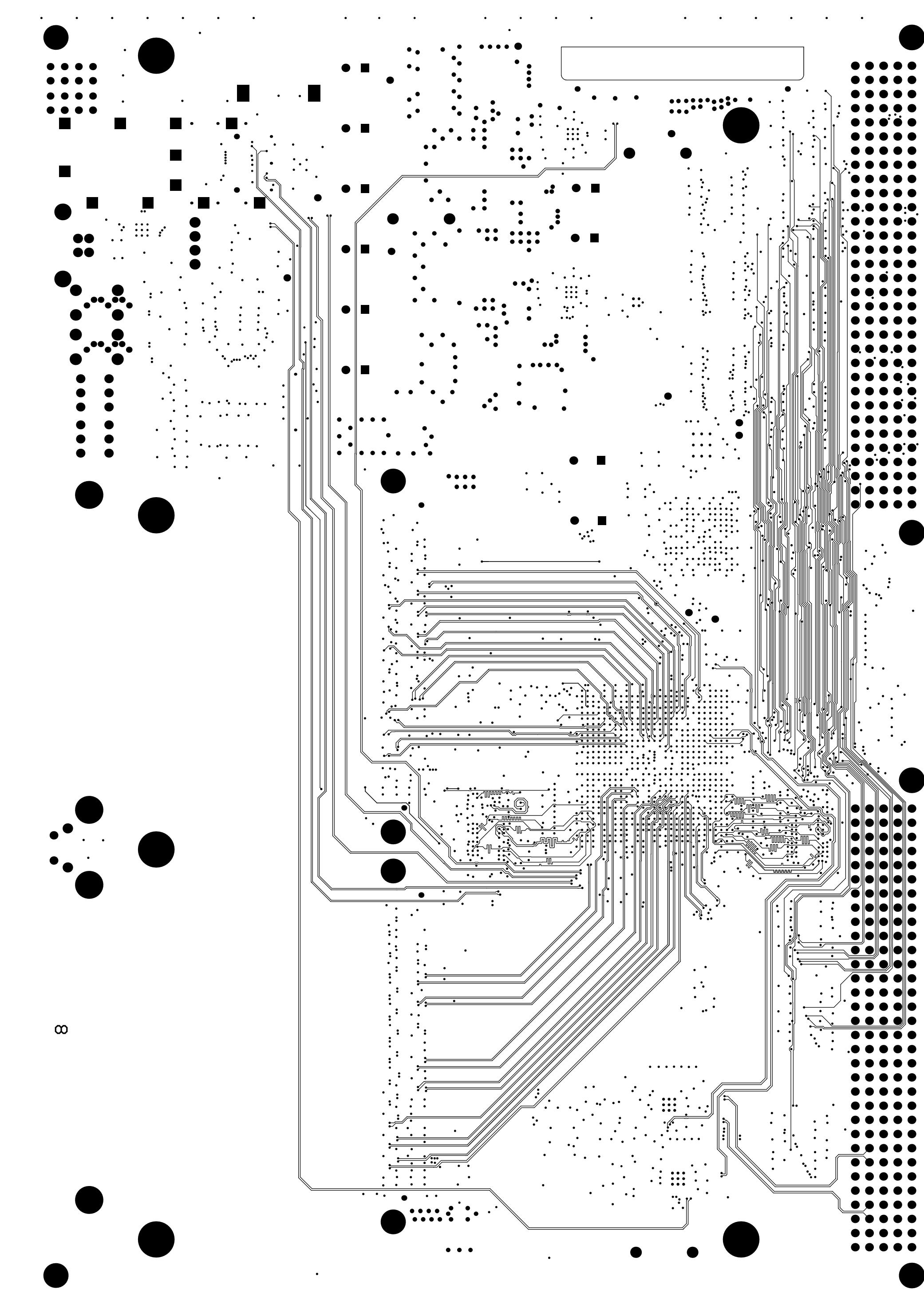


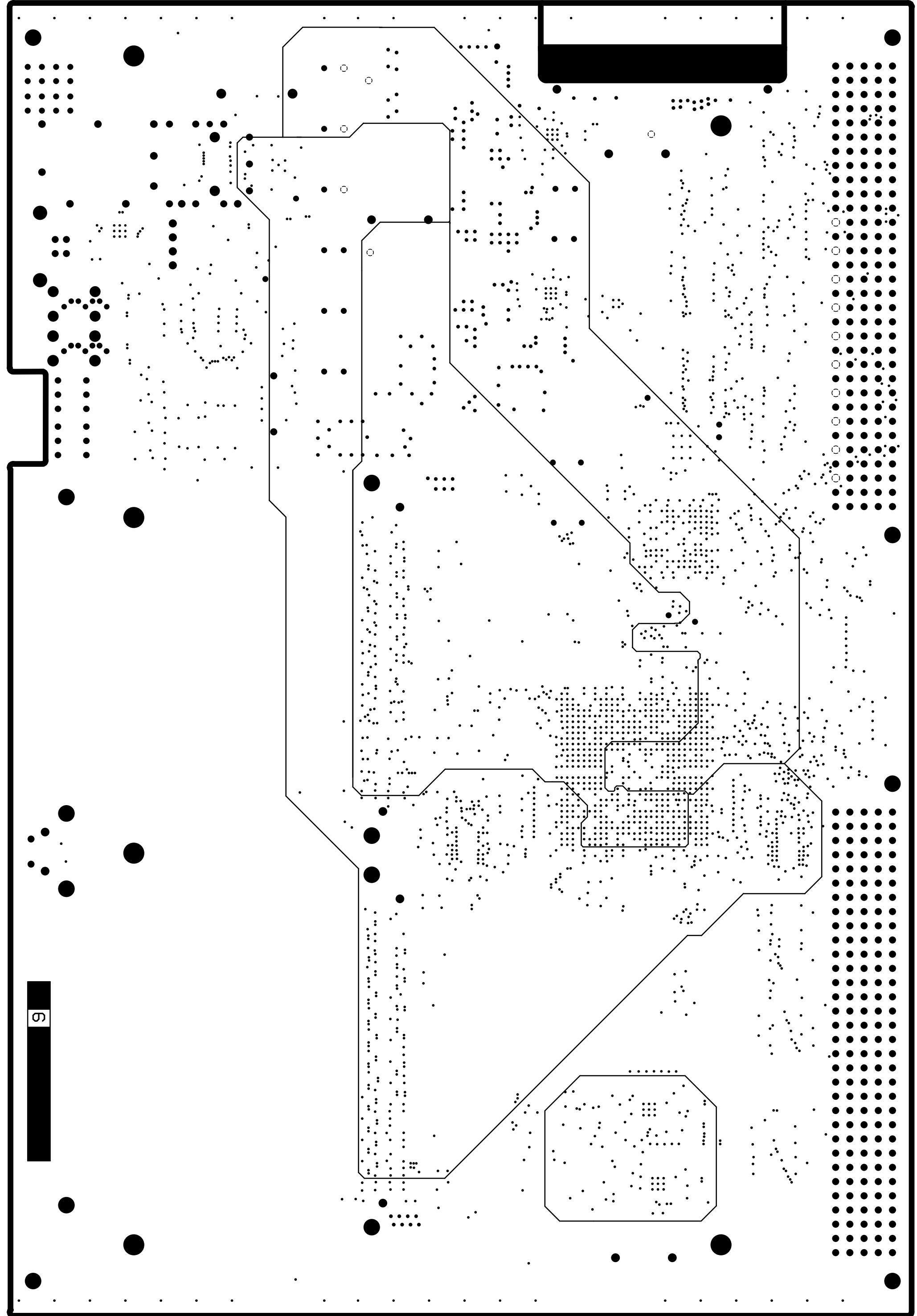


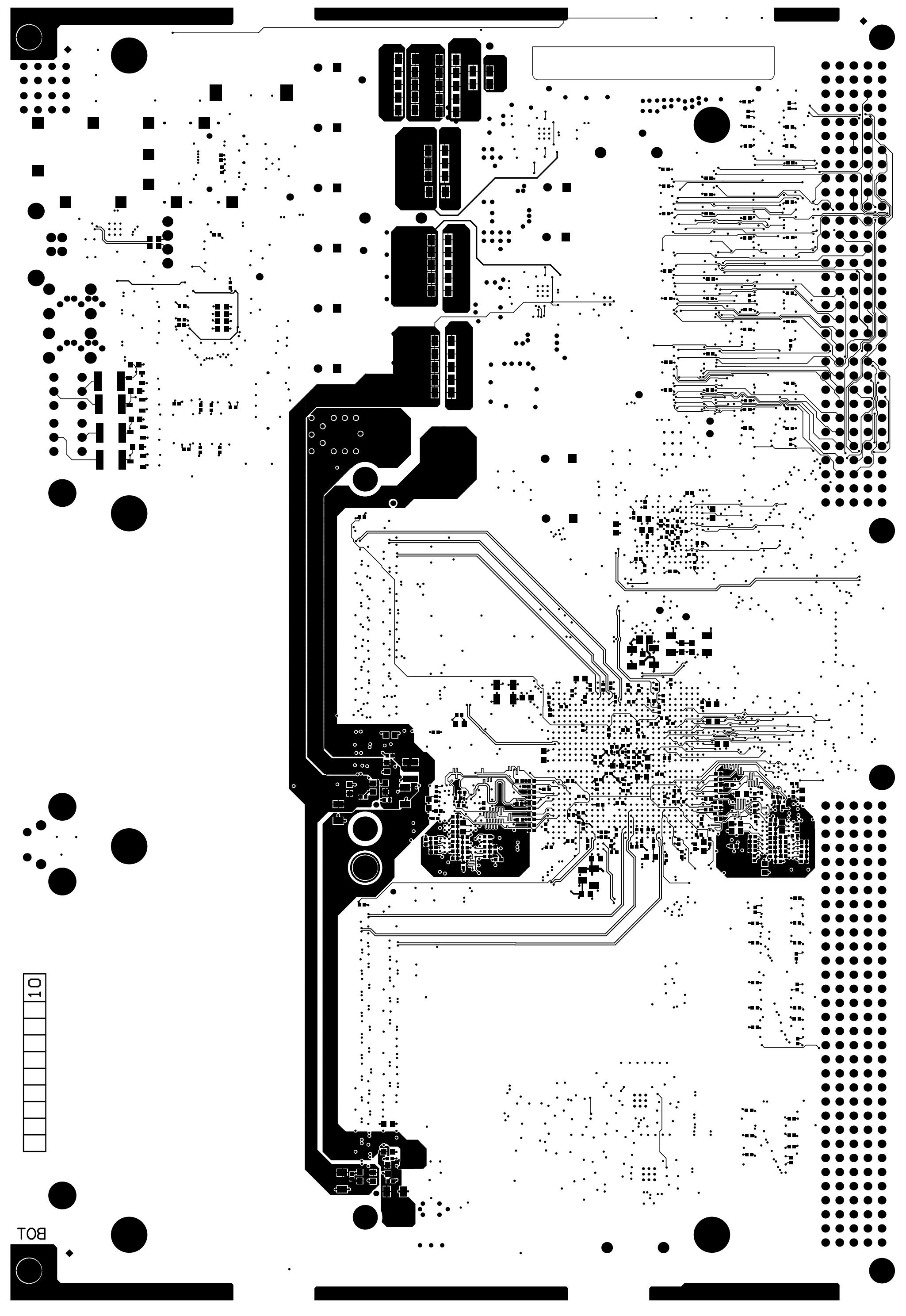












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